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PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of
Lloyd G. Burrell et al.

Serial No.: 09/805,027

Group Art Unit: 2822

Filed: March 12, 2001

Examiner: M. Lewis

For: COPPER TO ALUMINUM INTERLAYER INTERCONNECT USING
STUD AND VIA LINER

Commissioner for Patents
United States Patent and Trademark Office
P. O. Box 1450
Alexandria, Virginia 22313-1450

AMENDMENT WITH REQUEST FOR CONTINUED EXAMINATION

Sir:

Further in response to the Office Action mailed April 18, 2003, a Request for Continued Examination is being concurrently filed herewith. Additionally, please amend the above-identified application as follows:

Amendments to the specification begin on page 2 of this paper.

Amendments to the claims begin on page 3 of this paper.

No amendments to the Drawings are presented in this paper.

Remarks begin on page 5 of this paper.

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